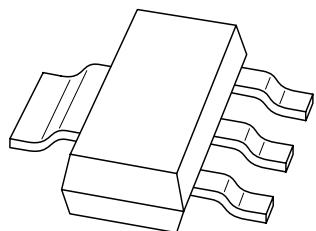


DATA SHEET



PZTA92 PNP high-voltage transistor

Product specification
Supersedes data of 1997 May 22

1999 Apr 14

PNP high-voltage transistor**PZTA92****FEATURES**

- Low current (max. 100 mA)
- High voltage (max. 300 V).

APPLICATIONS

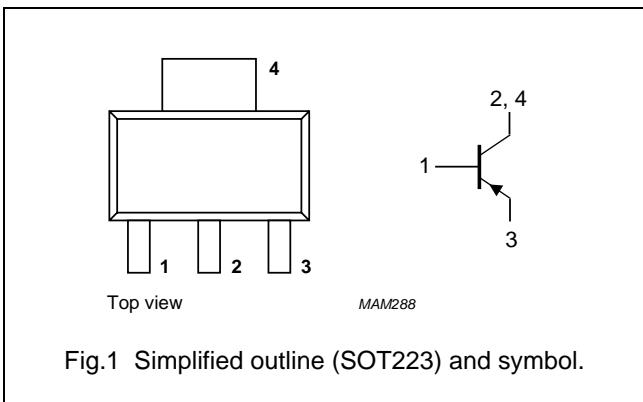
- Video equipment
- Telephony
- Professional communication equipment.

DESCRIPTION

PNP high-voltage transistor in a SOT223 plastic package.
NPN complement: PZTA42.

PINNING

PIN	DESCRIPTION
1	base
2, 4	collector
3	emitter



MAM288

Top view

Fig.1 Simplified outline (SOT223) and symbol.

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter	–	-300	V
V_{CEO}	collector-emitter voltage	open base	–	-300	V
V_{EBO}	emitter-base voltage	open collector	–	-5	V
I_C	collector current (DC)		–	-100	mA
I_{CM}	peak collector current		–	-200	mA
I_{BM}	peak base current		–	-100	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25^\circ\text{C}$; note 1	–	1.2	W
T_{sig}	storage temperature		-65	+150	°C
T_j	junction temperature		–	150	°C
T_{amb}	operating ambient temperature		-65	+150	°C

Note

1. Device mounted on a printed-circuit board, single-sided copper, tinplated, mounting pad for collector 1 cm².
For other mounting conditions, see "Thermal considerations for SOT223 in the General Part of associated Handbook".

PNP high-voltage transistor

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THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j-a}$	thermal resistance from junction to ambient	note 1	104	K/W
$R_{th\ j-s}$	thermal resistance from junction to soldering point		23	K/W

Note

1. Device mounted on a printed-circuit board, single-sided copper, tinplated, mounting pad for collector 1 cm². For other mounting conditions, see "Thermal considerations for SOT223 in the General Part of associated Handbook".

CHARACTERISTICS $T_{amb} = 25^\circ C$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I_{CBO}	collector cut-off current	$I_E = 0; V_{CB} = -200 V$	–	-20	nA
I_{EBO}	emitter cut-off current	$I_C = 0; V_{BE} = -5 V$	–	-100	nA
h_{FE}	DC current gain	$I_C = -1 mA; V_{CE} = -10 V; \text{note 1}$	25	–	
		$I_C = -10 mA; V_{CE} = -10 V; \text{note 1}$	40	–	
		$I_C = -30 mA; V_{CE} = -10 V; \text{note 1}$	25	–	
V_{CEsat}	collector-emitter saturation voltage	$I_C = -20 mA; I_B = -2 mA$	–	-500	mV
V_{BESat}	base-emitter saturation voltage	$I_C = -20 mA; I_B = -2 mA$	–	-900	mV
C_c	collector capacitance	$I_E = 0; V_{CB} = -20 V; f = 1 MHz$	–	6	pF
f_T	transition frequency	$I_C = -10 mA; V_{CE} = -20 V; f = 100 MHz$	50	–	MHz

Note

1. Pulse test: $t_p \leq 300 \mu s$; $\delta \leq 0.02$.

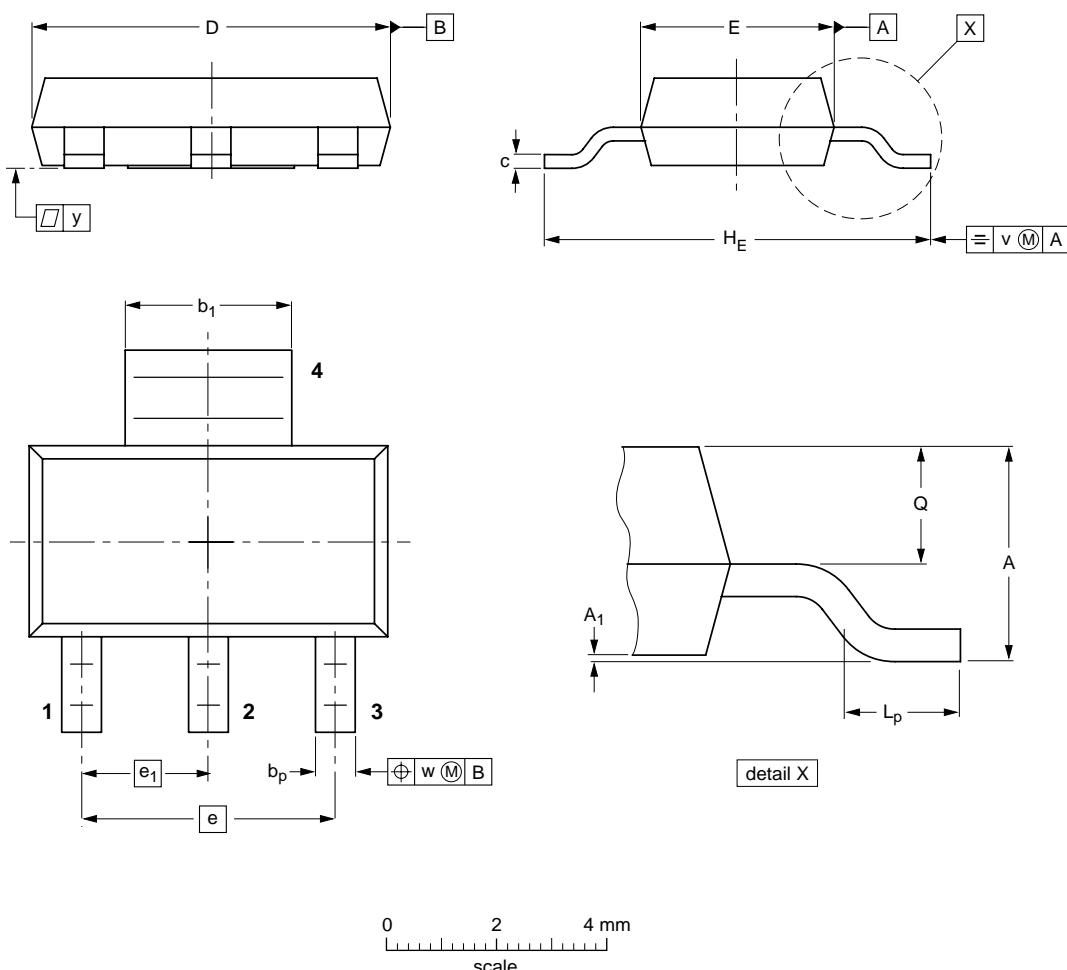
PNP high-voltage transistor

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PACKAGE OUTLINE

Plastic surface mounted package; collector pad for good heat transfer; 4 leads

SOT223



DIMENSIONS (mm are the original dimensions)

UNIT	A	A_1	b_p	b_1	c	D	E	e	e_1	H_E	L_p	Q	v	w	y
mm	1.8 1.5	0.10 0.01	0.80 0.60	3.1 2.9	0.32 0.22	6.7 6.3	3.7 3.3	4.6	2.3	7.3 6.7	1.1 0.7	0.95 0.85	0.2	0.1	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ	SC-73		
SOT223						-97-02-28 99-09-13